

# Single N Channel MOSFET

## Features

- Advanced Trench MOS Technology
- 100% EAS Guaranteed
- Fast Switching Speed
- Green Device Available

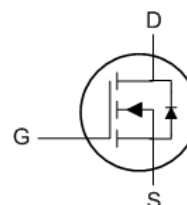
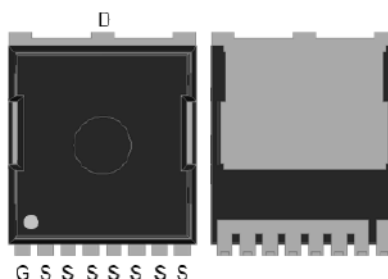
## Applications

- Power Tools.
- Motor Control.
- UPS.
- Synchronous Rectification in SMPS.

## Product Summary

BVDSS	RDSON	ID
100V	1.9mΩ	316A

## TOLL Pin Configuration



## Absolute Maximum Ratings

Symbol	Parameter	Rating	Units
$V_{DS}$	Drain-Source Voltage	100	V
$V_{GS}$	Gate-Source Voltage	±20	V
$I_D@T_C=25^\circ C$	Continuous Drain Current <sup>1,6</sup>	316	A
$I_D@T_C=100^\circ C$	Continuous Drain Current <sup>1,6</sup>	224	A
$I_D@T_A=25^\circ C$	Continuous Drain Current <sup>1</sup>	34	A
$I_D@T_A=70^\circ C$	Continuous Drain Current <sup>1</sup>	28	A
$I_{DM}$	Pulsed Drain Current <sup>2</sup>	1000	A
EAS	Single Pulse Avalanche Energy <sup>3</sup>	800	mJ
$I_{AS}$	Avalanche Current	40	A
$P_D@T_C=25^\circ C$	Total Power Dissipation <sup>4</sup>	333	W
$P_D@T_C=100^\circ C$	Total Power Dissipation <sup>4</sup>	166	W
$P_D@T_A=25^\circ C$	Total Power Dissipation <sup>4</sup>	3.8	W
$P_D@T_A=70^\circ C$	Total Power Dissipation <sup>4</sup>	2.6	W
$T_{STG}$	Storage Temperature Range	-55 to 175	°C
$T_J$	Operating Junction Temperature Range	-55 to 175	°C

## Thermal Data

Symbol	Parameter	Typ.	Max.	Unit
$R_{\theta JA}$	Thermal Resistance Junction-Ambient <sup>1</sup>	---	40	°C/W
$R_{\theta JC}$	Thermal Resistance Junction-Case <sup>1</sup>	---	0.45	°C/W

**Electrical Characteristics (T<sub>J</sub>=25 °C, unless otherwise noted)**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V, I <sub>D</sub> =250uA	100	---	---	V
R <sub>DS(ON)</sub>	Static Drain-Source On-Resistance <sup>2</sup>	V <sub>GS</sub> =10V, I <sub>D</sub> =90A	---	1.6	1.9	mΩ
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>GS</sub> =V <sub>DS</sub> , I <sub>D</sub> =250uA	2	---	4	V
I <sub>DSS</sub>	Drain-Source Leakage Current	V <sub>DS</sub> =80V, V <sub>GS</sub> =0V, T <sub>J</sub> =25°C	---	---	1	uA
		V <sub>DS</sub> =80V, V <sub>GS</sub> =0V, T <sub>J</sub> =100°C	---	---	100	
I <sub>GSS</sub>	Gate-Source Leakage Current	V <sub>GS</sub> =±20V, V <sub>DS</sub> =0V	---	---	±100	nA
g <sub>fs</sub>	Forward Transconductance	V <sub>DS</sub> =5V, I <sub>D</sub> =20A	---	75	---	S
Q <sub>g</sub>	Total Gate Charge	V <sub>DS</sub> =50V, V <sub>GS</sub> =10V, I <sub>D</sub> =90A	---	212	---	nC
Q <sub>gs</sub>	Gate-Source Charge		---	59	---	
Q <sub>gd</sub>	Gate-Drain Charge		---	53	---	
T <sub>d(on)</sub>	Turn-On Delay Time	V <sub>DD</sub> =50V, V <sub>GS</sub> =10V, R <sub>G</sub> =3Ω, I <sub>D</sub> =20A	---	47	---	ns
T <sub>r</sub>	Rise Time		---	28	---	
T <sub>d(off)</sub>	Turn-Off Delay Time		---	79	---	
T <sub>f</sub>	Fall Time		---	18	---	
C <sub>iss</sub>	Input Capacitance	V <sub>DS</sub> =50V, V <sub>GS</sub> =0V, f=1MHz	---	13362	---	pF
C <sub>oss</sub>	Output Capacitance		---	1917	---	
C <sub>rss</sub>	Reverse Transfer Capacitance		---	387	---	

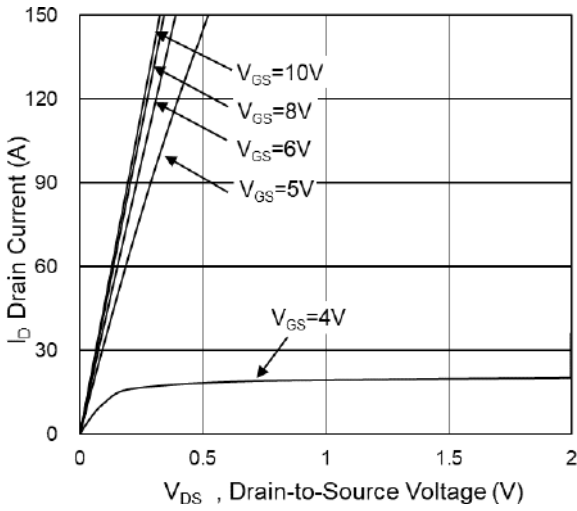
**Diode Characteristics**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
I <sub>S</sub>	Continuous Source Current <sup>1,5,6</sup>	V <sub>G</sub> =V <sub>D</sub> =0V, Force Current	---	---	100	A
V <sub>SD</sub>	Diode Forward Voltage <sup>2</sup>	V <sub>GS</sub> =0V, I <sub>S</sub> =1A, T <sub>J</sub> =25°C	---	---	1.1	V
t <sub>r</sub>	Reverse Recovery Time	I <sub>F</sub> =20A, di/dt=100A/μs,	---	70	---	nS
Q <sub>rr</sub>	Reverse Recovery Charge	T <sub>J</sub> =25°C	---	580	---	nC

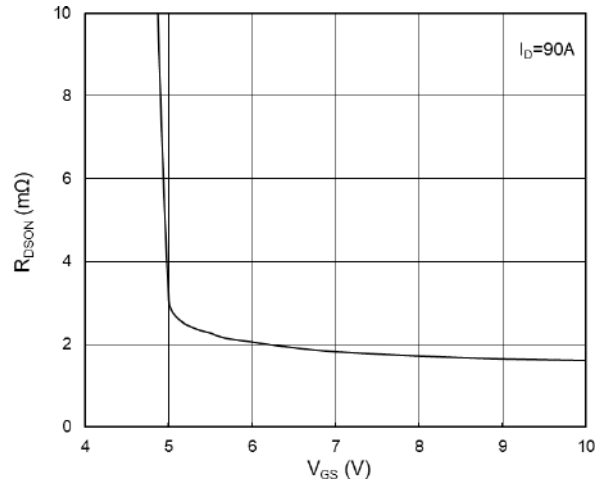
Note :

1. The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper.
2. The data tested by pulsed, pulse width ≤ 300us, duty cycle ≤ 2%
3. The EAS data shows Max. rating. The test condition is V<sub>DD</sub>=50V, V<sub>GS</sub>=10V, L=1.0mH, I<sub>AS</sub>=40A
4. The power dissipation is limited by 175°C junction temperature.
5. The data is theoretically the same as I<sub>D</sub> and I<sub>DM</sub>, in real applications, should be limited by total power dissipation.
6. Package limitation current is 300A.

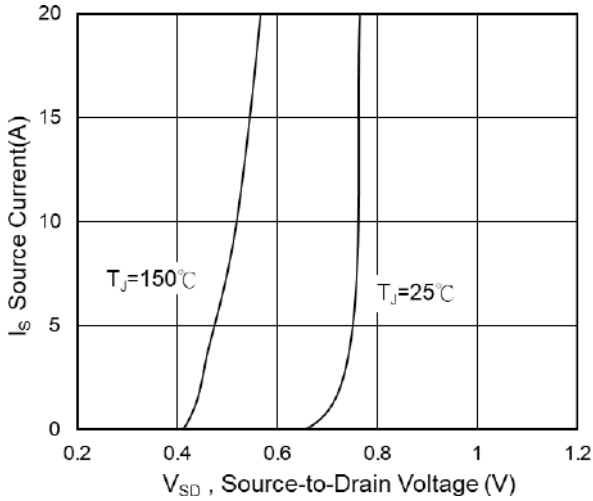
**Typical Characteristics**



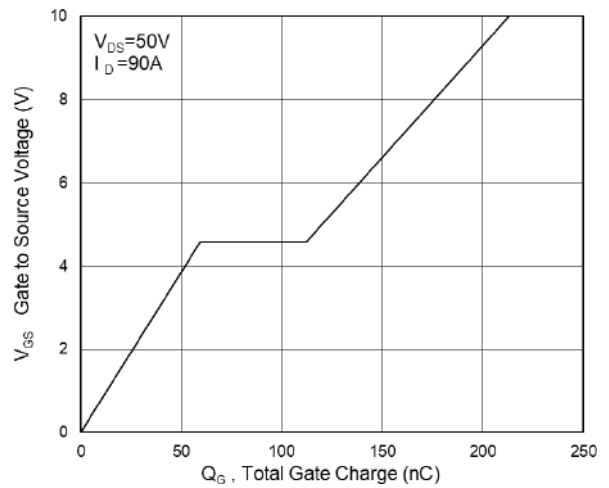
**Fig.1 Typical Output Characteristics**



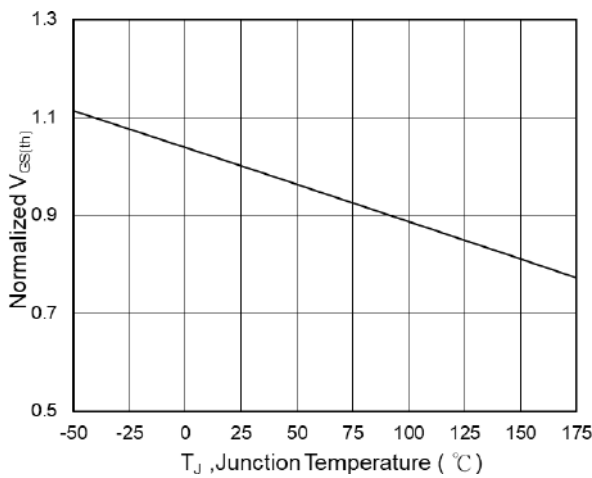
**Fig.2 On-Resistance vs G-S Voltage**



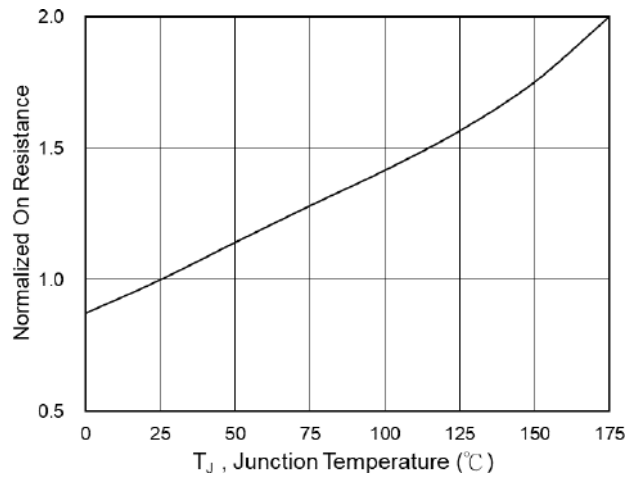
**Fig.3 Source-Drain Forward Characteristics**



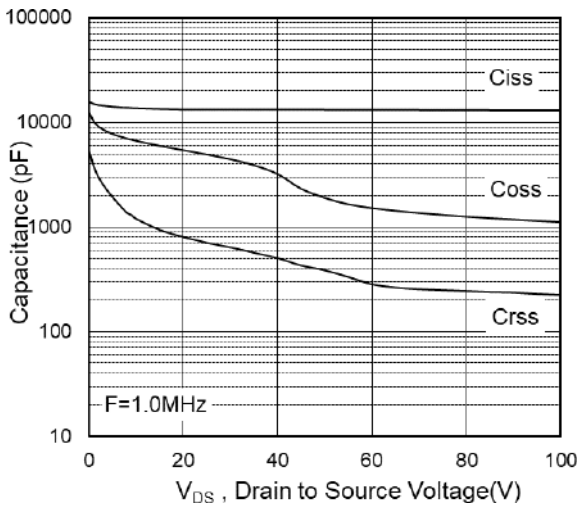
**Fig.4 Gate-Charge Characteristics**



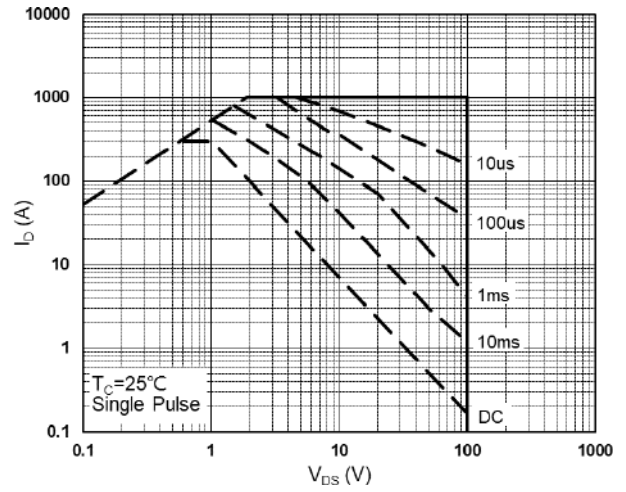
**Fig.5 Normalized  $V_{GS(th)}$  vs  $T_J$**



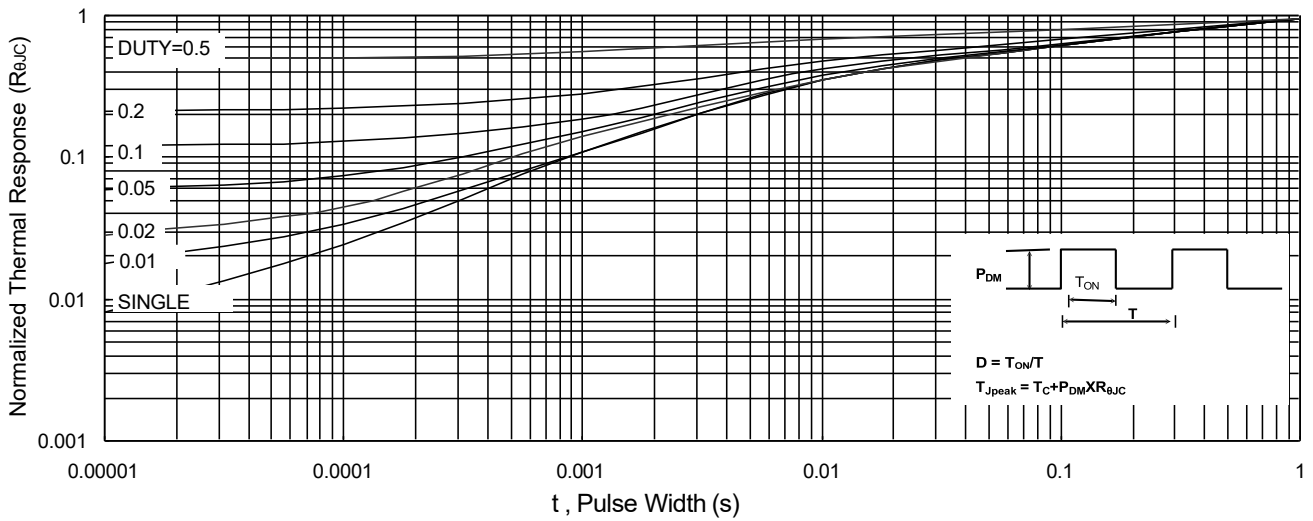
**Fig.6 Normalized  $R_{DS(on)}$  vs  $T_J$**



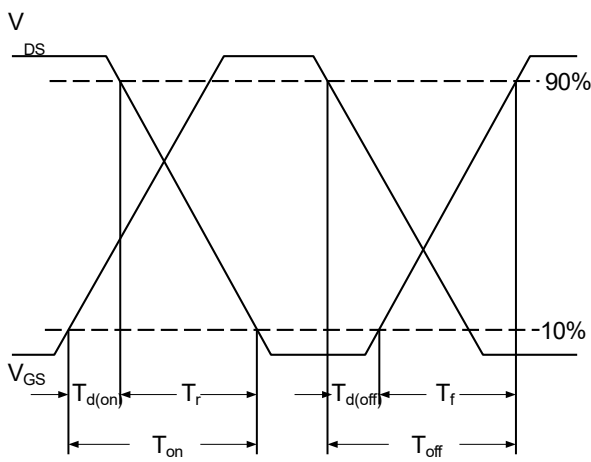
**Fig.7 Capacitance**



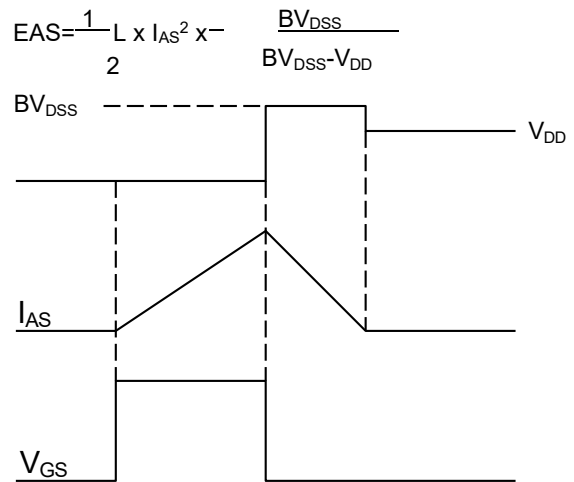
**Fig.8 Safe Operating Area**



**Fig.9 Normalized Maximum Transient Thermal Impedance**



**Fig.10 Switching Time Waveform**



**Fig.11 Unclamped Inductive Switching Waveform**